
ABSTRACT OF THE DISCLOSURE

A soldering method including: bonding a first electronic component having electrodes plated with a material containing lead to one surface of an interconnect substrate through solder containing no lead; and flow-soldering to bond a second electronic component to the other surface of the interconnect substrate. In the soldering method, a joint section between the first electronic component and the interconnect substrate is heated at the same time as or after the step of flow soldering to melt the joint section.